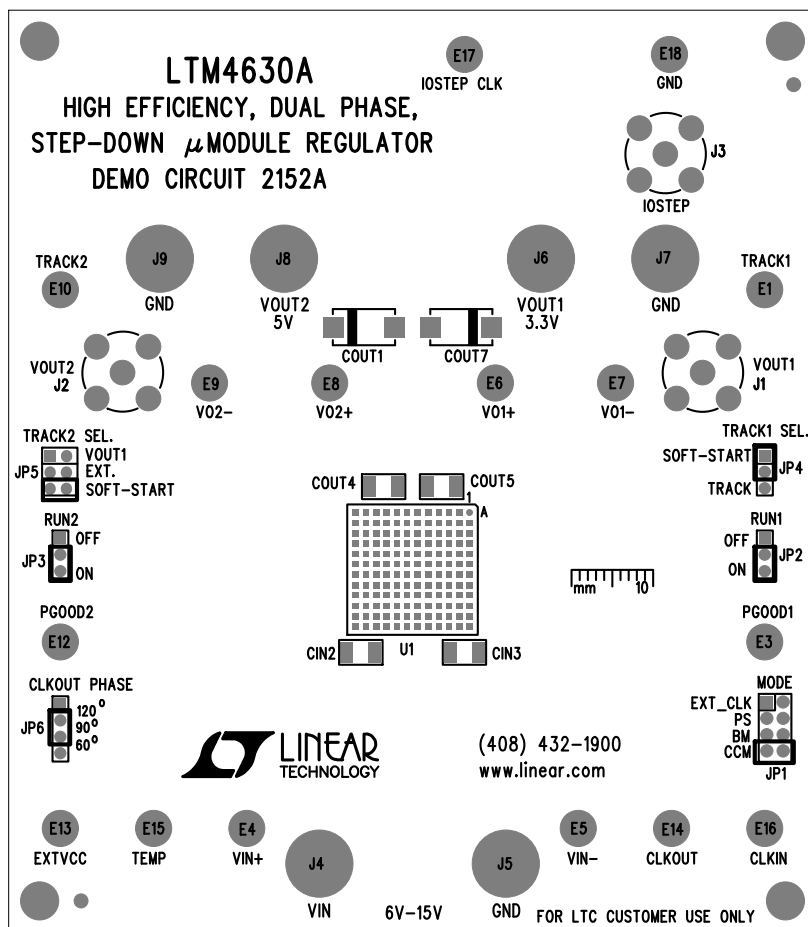
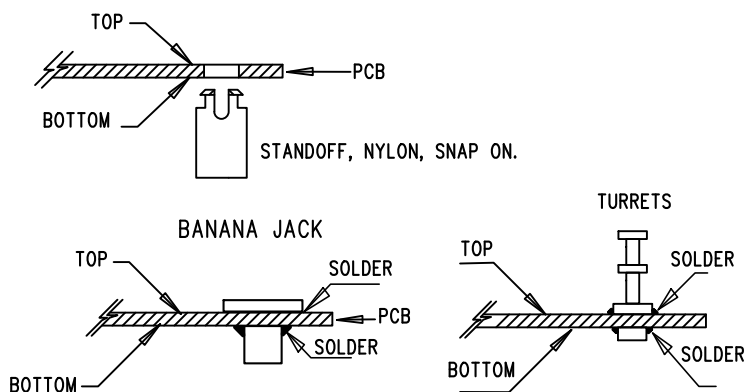



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	YINGYI L.	10-06-14



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS, BANANA JACK, TURRETS.



APPROVALS		 <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>		
PCB DES.	LT	TITLE: TOP ASSEMBLY DRAWING HIGH EFFICIENCY, DUAL PHASE, STEP-DOWN μ MODULE REGULATOR		
APP ENG.	YINGYI Y.			
		SIZE	IC NO. LTM4630AEV	REV. 1
		N/A	DEMO CIRCUIT 2152A	
SCALE = NONE		FILENAME: DC2152A-1.PCB		SHT 1 OF 2